LEAD FRAME, MANUFACTURING METHOD OF A LEAD FRAME, SEMICONDUCTOR DEVICE, ASSEMBLING METHOD OF A SEMICONDUCTOR DEVICE, AND ELECTRONIC APPARATUS

ABSTRACT OF THE DISCLOSURE

Metal films (for instance, gold films or palladium films) to constitute bumps are formed on a metal base by electrolytic plating. Then, a circuit wiring including inner leads is formed by electrolytic plating with a metal so that the inner leads are connected to the respective metal films.

Figure 1